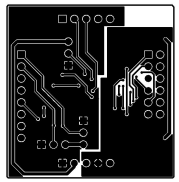
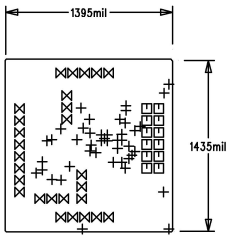


EVAL-AD5144DBZ Component Side View – Rev. A
Component Side – Layer 1



EVAL-AD5144DBZ Component Side View – Rev. A

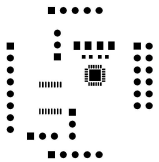
Solder side – Layer 2



EVAL-AD5144DBZ Component Side View – Rev. A
Component Side – Layer 1
Drill Template

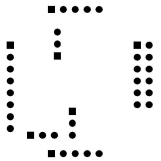
1. Material: Two layer, FR4 glass epoxy laminate, 0.039" +/-.003" thick.
   1 oz. copper clad both sides.
   Material shall be RoHS compliant.
2. Plated thru holes and the conductive pattern electroplated with 0.001" min. thick copper. Terminal areas and plated thru holes to be ENIG plated.
   Soldermask over bare copper.
3. Finished Board shall be RoHS Compliant
4. Datum for (x,y) co-ordinate drill files at LLH corner.
5. Processing tolerances:
   A. Conductive pattern front to back registration within .005" total.
   B. Minimum annular ring surrounding holes: 0.002"
   C. Finished conductive pattern within .002" of true size.
6. Warp and twist within .010 inch per inch
7. Dimensions are for the finished part.
8. Solder Mask: Liquid photo imagable solder mask over bare copper (smobc), colour green, both sides using the patterns provided. No mask is permitted on the terminal areas. Soldermask to etch registration within .005" total.
9. Screening: Screen component outlines and nomenclature using indelible white ink on the primary side only. Nomenclature shall be legible.
   Screen to etch registration within .010" total.
10. Surfaces: Punched or machined surfaces 125 micro inches rms max.
11. Break all sharp edges .015" R max.

SIZE	QTY	SYM	PLATED	TOL
10	44	┼	YES	+/-0.0
37	12	⊡	YES	+/-0.0
35	27	⋈	YES	+/-0.0



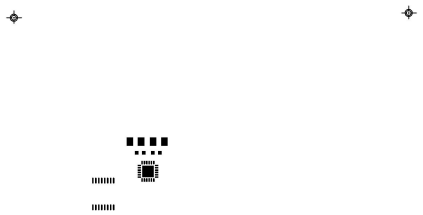
EVAL-AD5144DBZ Component Side View – Rev. A

Component Side Soldermask



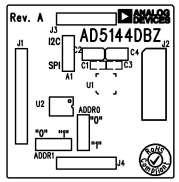
EVAL-AD5144DBZ Component Side View – Rev. A

Solderside Soldermask



EVAL-AD5144DBZ Component Side View – Rev. A

Component Side Pastemask



EVAL-AD5144DBZ Component Side View – Rev. A
Silkscreen